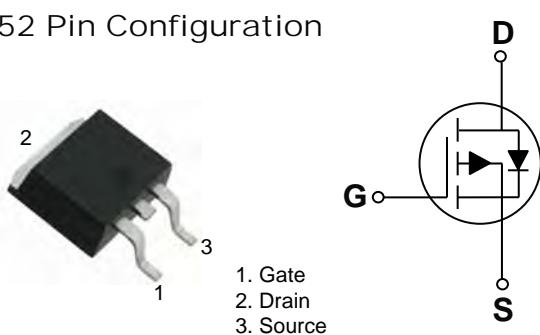


40V P-Channel MOSFETs

General Description

These P-Channel enhancement mode power field effect transistors are using trench DMOS technology. This advanced technology has been especially tailored to minimize on-state resistance, provide superior switching performance, and withstand high energy pulse in the avalanche and commutation mode. These devices are well suited for high efficiency fast switching applications.

TO-252 Pin Configuration



BVDSS	RDS(ON)	ID
-40V	5.8mΩ	-90A

Features

- -40V, -90A, RDS(ON) = 5.8mΩ @ VGS = -10V
- Fast switching
- Green Device Available
- Suit for -4.5V Gate Drive Applications

Applications

- Notebook
- Load Switch
- Battery Protection
- Hand-held Instruments

Absolute Maximum Ratings (Tc=25°C unless otherwise noted)

Symbol	Parameter	Rating	Units
V _{DS}	Drain-Source Voltage	-40	V
V _{GS}	Gate-Source Voltage	±20	V
I _D	Drain Current – Continuous (Tc=25 °C)	-90	A
	Drain Current – Continuous (Tc=100 °C)	-57	A
I _{DM}	Drain Current – Pulsed ¹	-360	A
EAS	Single Pulse Avalanche Energy ²	174	mJ
IAS	Single Pulse Avalanche Current ²	-59	A
P _D	Power Dissipation (Tc=25 °C)	101	W
	Power Dissipation – Derate above 25 °C	0.81	W/°C
T _{STG}	Storage Temperature Range	-55 to 150	°C
T _J	Operating Junction Temperature Range	-55 to 150	°C

Thermal Characteristics

Symbol	Parameter	Typ.	Max.	Unit
R _{JA}	Thermal Resistance Junction to Ambient	---	62	°C/W
R _{JC}	Thermal Resistance Junction to Case	---	1.23	°C/W



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40V P-Channel MOSFETs

Electrical Characteristics ($T_J=25^\circ\text{C}$, unless otherwise noted)

Off Characteristics

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
BV_{DSS}	Drain-Source Breakdown Voltage	$V_{\text{GS}}=0\text{V}$, $I_{\text{D}}=-250\mu\text{A}$	-40	---	---	V
I_{DSS}	Drain-Source Leakage Current	$V_{\text{DS}}=-40\text{V}$, $V_{\text{GS}}=0\text{V}$, $T_J=25^\circ\text{C}$	---	---	-1	μA
		$V_{\text{DS}}=-32\text{V}$, $V_{\text{GS}}=0\text{V}$, $T_J=125^\circ\text{C}$	---	---	-10	μA
I_{GSS}	Gate-Source Leakage Current	$V_{\text{GS}}=\pm 20\text{V}$, $V_{\text{DS}}=0\text{V}$	---	---	± 100	nA

On Characteristics

$R_{\text{DS(ON)}}$	Static Drain-Source On-Resistance	$V_{\text{GS}}=-10\text{V}$, $I_{\text{D}}=-25\text{A}$	---	4.7	5.8	$\text{m}\Omega$
		$V_{\text{GS}}=-4.5\text{V}$, $I_{\text{D}}=-15\text{A}$	---	6.4	8.3	$\text{m}\Omega$
$V_{\text{GS(th)}}$	Gate Threshold Voltage	$V_{\text{GS}}=V_{\text{DS}}$, $I_{\text{D}}=-250\mu\text{A}$	-1.2	-1.6	-2.5	V
g_{fs}	Forward Transconductance	$V_{\text{DS}}=-10\text{V}$, $I_{\text{D}}=-3\text{A}$	---	15	---	S

Dynamic and switching Characteristics

Q_g	Total Gate Charge ^{3, 4}	$V_{\text{DS}}=-20\text{V}$, $V_{\text{GS}}=-10\text{V}$, $I_{\text{D}}=-45\text{A}$	---	115	160	nC
Q_{gs}	Gate-Source Charge ^{3, 4}		---	16	25	
Q_{gd}	Gate-Drain Charge ^{3, 4}		---	25	40	
$T_{\text{d(on)}}$	Turn-On Delay Time ^{3, 4}	$V_{\text{DD}}=-20\text{V}$, $V_{\text{GS}}=-10\text{V}$, $R_{\text{G}}=6\Omega$	---	41.6	82	ns
T_r	Rise Time ^{3, 4}		---	12.7	26	
$T_{\text{d(off)}}$	Turn-Off Delay Time ^{3, 4}		---	308	600	
T_f	Fall Time ^{3, 4}		---	70	140	
C_{iss}	Input Capacitance	$V_{\text{DS}}=-20\text{V}$, $V_{\text{GS}}=0\text{V}$, $F=1\text{MHz}$	---	6100	9100	pF
C_{oss}	Output Capacitance		---	600	900	
C_{rss}	Reverse Transfer Capacitance		---	540	810	
R_g	Gate resistance	$V_{\text{GS}}=0\text{V}$, $V_{\text{DS}}=0\text{V}$, $F=1\text{MHz}$	---	4.2	---	Ω

Drain-Source Diode Characteristics and Maximum Ratings

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
I_s	Continuous Source Current	$V_G=V_D=0\text{V}$, Force Current	---	---	-90	A
	Pulsed Source Current		---	---	-180	A
V_{SD}	Diode Forward Voltage	$V_{\text{GS}}=0\text{V}$, $I_s=-1\text{A}$, $T_J=25^\circ\text{C}$	---	---	-1	V
t_{rr}	Reverse Recovery Time	$V_R=30\text{V}$, $I_s=10\text{A}$	---	60	---	ns
Q_{rr}	Reverse Recovery Charge	$\text{di/dt}=100\text{A}/\mu\text{s}$, $T_J=25^\circ\text{C}$	---	55	---	nC

Note :

1. Repetitive Rating : Pulsed width limited by maximum junction temperature.
2. $V_{\text{DD}}=-25\text{V}$, $V_{\text{GS}}=-10\text{V}$, $L=0.1\text{mH}$, $I_{\text{AS}}=-59\text{A}$, $R_{\text{G}}=25\Omega$, Starting $T_J=25^\circ\text{C}$
3. The data tested by pulsed , pulse width $\leq 300\mu\text{s}$, duty cycle $\leq 2\%$.
4. Essentially independent of operating temperature.

40V P-Channel MOSFETs

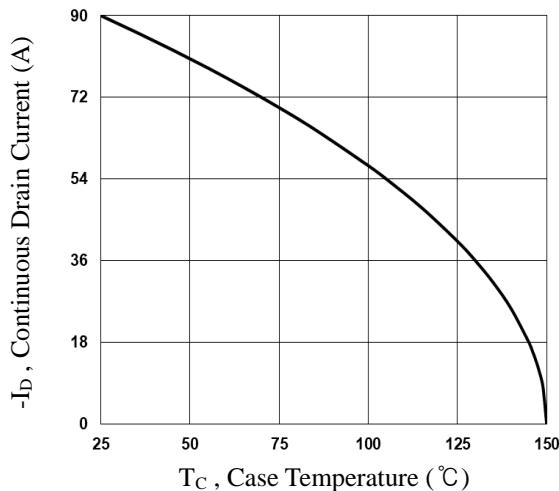


Fig.1 Continuous Drain Current vs. T_C

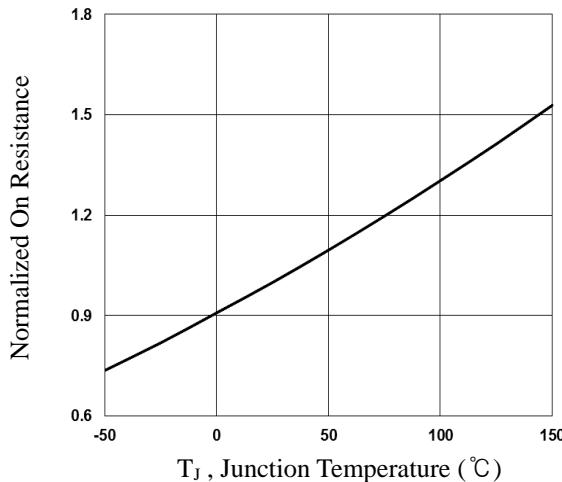


Fig.2 Normalized RDS(ON) vs. T_J

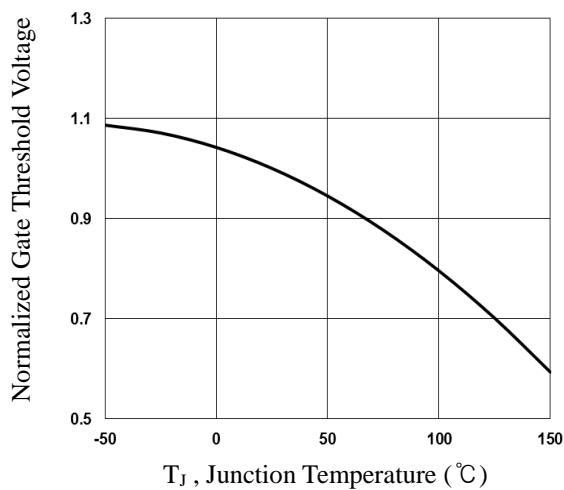


Fig.3 Normalized V_{th} vs. T_J

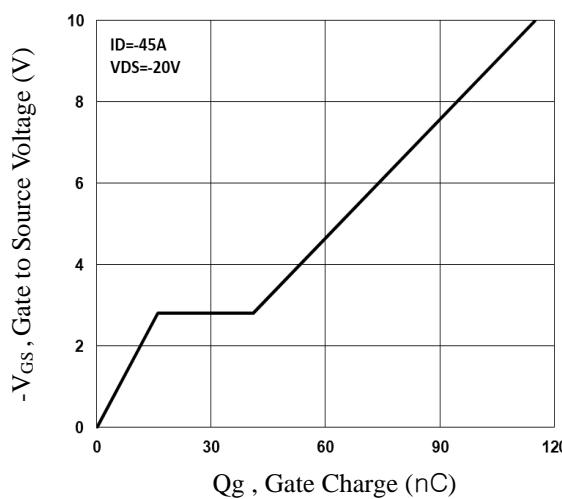


Fig.4 Gate Charge Waveform

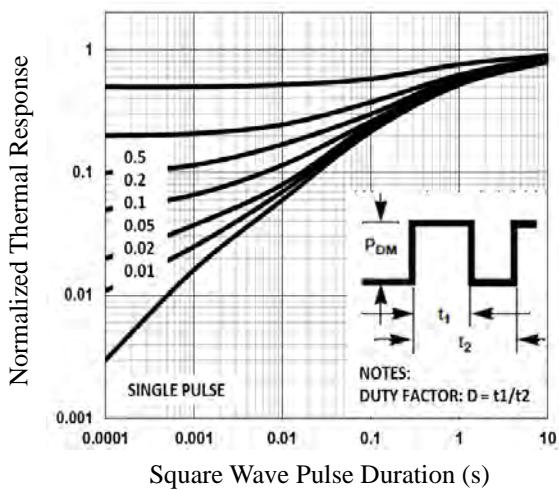


Fig.5 Normalized Transient Impedance

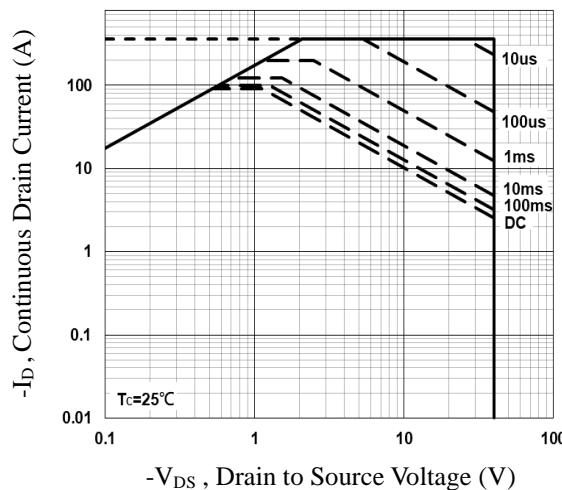


Fig.6 Maximum Safe Operation Area

40V P-Channel MOSFETs

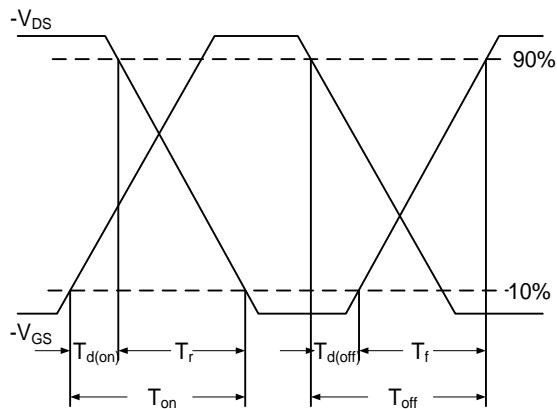


Fig.7 Switching Time Waveform

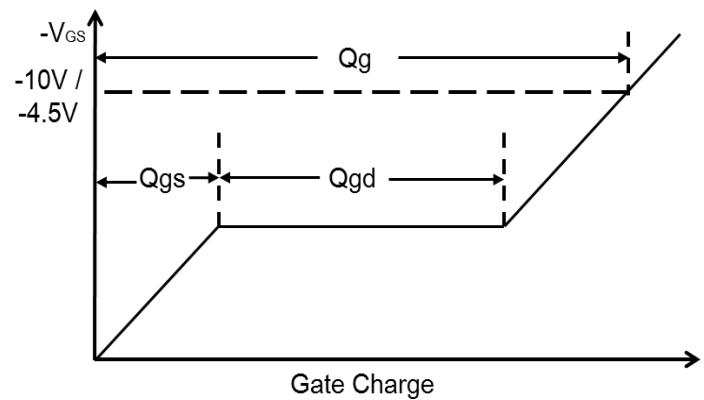
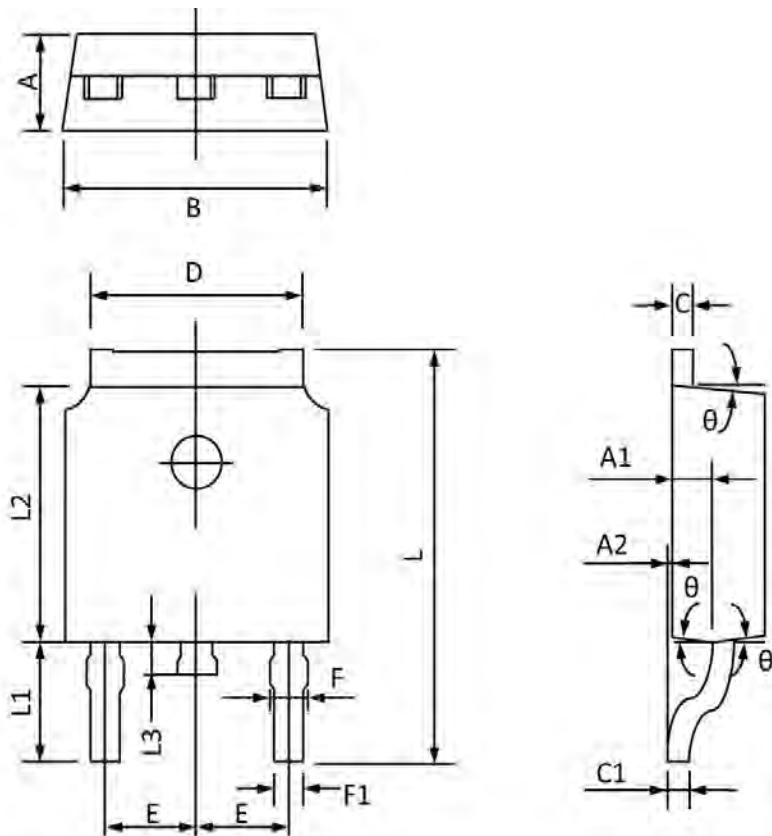


Fig.8 Gate Charge Waveform

40V P-Channel MOSFETs

TO-252 PACKAGE INFORMATION



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	MAX	MIN	MAX	MIN
A	2.450	2.150	0.096	0.085
A1	1.200	0.910	0.047	0.036
A2	0.150	0.000	0.006	0.000
B	6.800	6.300	0.268	0.248
C	0.580	0.350	0.023	0.014
C1	0.550	0.380	0.022	0.015
D	5.500	5.100	0.217	0.201
E	2.390	2.000	0.094	0.079
F	0.940	0.600	0.037	0.024
F1	0.860	0.500	0.034	0.020
L	10.400	9.400	0.409	0.370
L1	3.000	2.400	0.118	0.094
L2	6.200	5.300	0.244	0.209
L3	1.200	0.600	0.047	0.024
θ	9°	3°	9°	3°